

## Lec 1-2

### Introduction to VLSI

1. What is circuit integration? [Marks: 1]

Circuit integration is a technique that allows to build system with many more transistors allowing much more computing power to be applied to solve a problem.

2. What is Integrated Circuit (IC)?

IC is a device built with lots of transistors for allowing much more computing power to be applied to solve problem.

3. What are the advantages/importances of VLSI?

1. Integration improves the design in the following ways

a. Ckt contains lower parasitics, which results in higher speed.

b. Lower power consumption.

c. Physically smaller ckt.

2. Integration reduces manufacturing cost — (almost) manual assembly.

5-1-5

3. The integration of a large number of functions on a single chip usually provides:

- Less area/volume and therefore, compactness

- Less power consumption

- Less testing requirement at system level

- Higher reliability, mainly due to on-chip interconnects.

- Higher speed, due to significantly reduced interconnection length

- Significant cost savings.

4. What are the technologies used in VLSI?

1. TTL (Transistor-Transistor Logic)

2. ECL (Emitter Couple Logic)

3. MOS (Metal Oxide Semi-conductor)

4. Boolean Logic

5. What are the cost factors of IC?

1. For large-volume ICs:

- a. Packaging is the largest cost.

- b. Testing is the second-largest cost.

2. For low volume ICs, design costs may swamp all manufacturing costs.

6. Write down Moore's Law with its importance. [2007, Marks: 2]

ALSO, Explain Moore's Law in terms of Intel Microprocessors.

[In course 05-06 Marks: 2]

### Moore's Law:

The number of transistors per chip would grow exponentially (doubled every 18 months).

### Importance of Moore's Law:\*

The capabilities of many digital electronic devices are strongly linked to Moore's Law: processing speed, memory capacity etc. All of these are improving at (roughly) exponential rates. This has dramatically increased the usefulness of digital electronics in nearly every segment of the world economy. Moore's Law precisely describes a driving force of technological and social change in the late 20th and 21st centuries.

### Moore's Law applied in Intel Microprocessors.

The number of transistors in Intel microprocessors sizes of several generations starting from the Intel 8086 have grown exponentially almost every 18 months, which is a classic example of Moore's Law.

\* Taken from Wikipedia.

7. What are the challenges of VLSI design? [2008, 2006, Marks: 1]

1. Multiple levels of abstraction — transistors to CPUs.
2. Multiple and conflicting costs constraints — low costs and high performance are often at odds.
3. Short design time — late products are often irrelevant.

8. Explain the term "multiple and conflicting costs". [In-course 05-06, Marks: 1]

There are two cost measures of VLSI chip:

1. The speed at which the chip runs — two architectures which execute the same function (e.g. multiplication) may run at very different speeds.

2. Chip area — the cost of manufacturing a chip is exponentially related to its area.

Actual answer for 1 mark starts from here:

The mentioned term means that if ~~most~~ multiple cost ~~to~~ criteria — such as area and speed requirements — must be satisfied, many design decisions will improve one cost metric at the expense of the other.

Q. What do you understand by top-down design and bottom-up design?

A top-down approach essentially is the breaking down of a system to gain insight into its compositional subsystems (i.e. functional detail).

A bottom-up approach is the piecing together of systems to give rise to grander systems. Bottom-up design creates abstractions from low-level behavior.

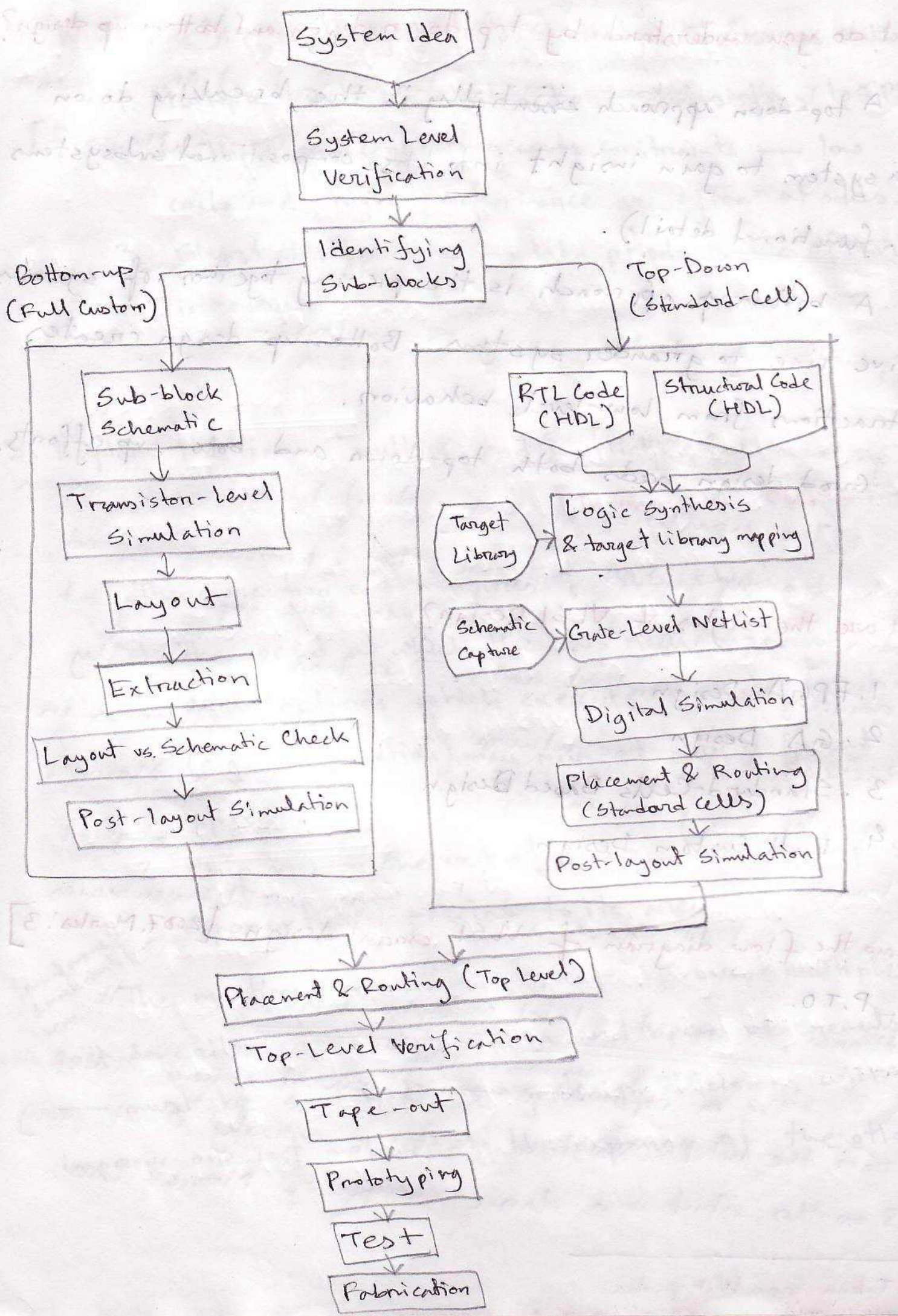
Good design needs both top-down and bottom-up efforts.

Q. What are the styles of VLSI Design?

1. FPGA Design
2. GA Design
3. Standard-Cells Based Design
4. Full Custom Design

1. Draw the flow diagram of VLSI circuit design. [2007. Marks: 3]

P.T.O.



What is netlist? [2007. Marks: 0.5]

What are the importances of netlist? [In-course 05-06. Marks: 1]

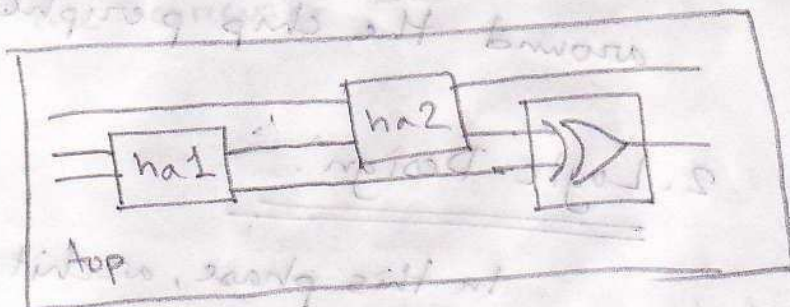
Netlist gives for each net the terminals connected to that net.

### Importance of netlist:

To understand how the system works, we only have to know each component's netlist (i.e., input-output behavior), not how that the behavior is implemented inside the box.

Construct a full-adder using two half-adders and write down its netlist. [2007. Marks: 2]

```
net1: top.in1 ha1.in1
leftin1: top.in2 ha1.in2
net2: top.in3 ha2.in1
s1 : ha1.out1 ha2.in2
net3 : ha2.out2 xor.in1
e1 : ha1.out2 xor.in2
outnet1: ha2.out2 top.out1
outnet2: xor.out1 top.out2
```



14. What are the VLSI IC design approaches?

- Design with Chips
- Full Custom Design
- Semi-custom Design

15. Describe each phases of full-custom design. [In-course, Marks: 4]

### 1. System Design:

The architecture is checked against the system specification to ensure that all required hardware features and data paths have been included. It is also usual to check that the ~~req~~ required number of input pins and output pins can be accommodated around the chip periphery.

### 2. Logic Design:

In this phase, architectural blocks are expanded into logic diagrams. Here each item drawn represents a particular logic function, such as a gate. Control and timing logic is also included at this level. Some simulation is also used to verify the logic function.



### 3. Circuit Design:

In this level, the logic is translated into circuits and dimension assigned to the translated <sup>circuit</sup>. Sometimes stick diagram is used to represent the circuit. Circuit simulation can verify the circuit at this level and provide an indication of power dissipation and heat.

### 4. Layout Design:

Once the circuit design is correct, the circuits are allocated to the positions on the silicon and geometric shapes are generated for each silicon layer corresponding to the circuits and their interconnections.

### 5. Fabrication:

After the geometric layout procedure is complete, the design normally passes out of the designer's hands. The data representation of the geometric layout is normally used to produce the mask of each silicon layer. The masks are then used at the different production stages of the fabrication process to produce the specified chip.

16. Describe the fabrication process. [In-course 05-06, Marks 13]

[See the prev. ques.]

17. Why logic design is placed before circuit design in full-custom design approach? Discuss with example.

[2007, 2006, Marks 12]

Circuit design is the implementation of logic design. After all the logic of all the components are designed, the whole circuit is implemented.

Hence, circuit design logic design is placed before circuit design.

Fabrication

After the geometric layout procedure is complete, the design is normally passed out of the designer's hands. The data representation of the geometric layout is normally used to produce the mask of each silicon layer. The masks are then used in the different production steps of the fabrication process to produce

## Lecture 3-4

### LOGIC SYNTHESIS, Queen McCluskey, BDD

1. What do you mean by logic synthesis? Write some logic synthesis techniques/tools. [2008, 2007, 2006, Marks: 2]

Logic synthesis is a process by which an abstract form of desired circuit behavior is turned into a design implementation in terms of logic gates.

Some logic synthesis techniques are - Karnaugh maps, Quine-McCluskey algorithm, Binary Decision Tree (BDT) etc.

2. What is essential prime implicant? [In-course 08-09, Marks: 1]

\* (Essential prime implicants are prime implicants that cover an output of the  $n$  input function that no combination of other prime implicants is able to cover.)

A product term is called essential prime implicant of input function if there is a minterm that is only covered by that prime implicant.

3. Write down the advantage of QM minimization over K-map minimization. [2006, Marks: 1/2]

~~While K-map can handle five or six input variables so~~

1. While K-map becomes very complex for input variables

greater than six, QM can handle any number of inputs.

2. Q-M happens to be nicely suited to a computerized

solution rather than K-map does.

4. What do you mean by Ordered BDD and ROBDD?

[2007, Marks: 2]

Ordered BDD:

A BDD is called 'ordered' if different variables appear in the same order on all paths from the root.

ROBDD:

A BDD is said to be 'reduced ordered' if it is an ordered BDD and the following two rules have been applied to its graph:

1. Merge any isomorphic subgraphs.
2. Eliminate any node whose children are isomorphic.

5. What is the advantage of ROBDD?

The advantage of ROBDD is that it is canonical (unique) for a particular functionality. This property makes it useful in functional equivalence checking and other operations like functional technology mapping.

6. Define BDD.

A BDD is a data structure that is used to represent a boolean function.

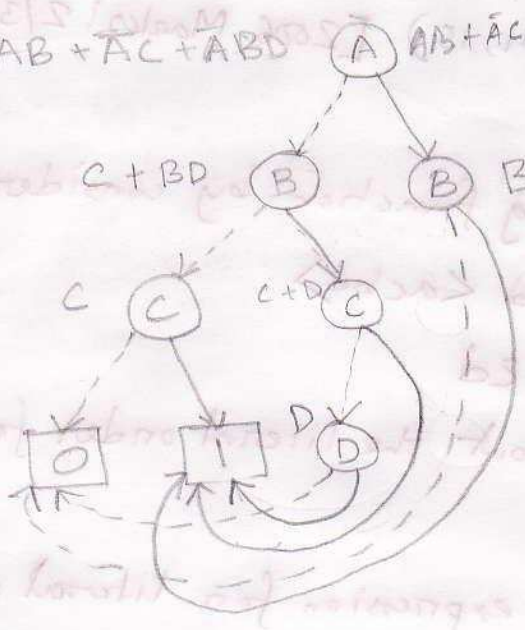
7. Draw the BDD for the following functions: [Marks: 1 per ch.]

i)  $F = AB + \bar{A}C + \bar{A}BD$  [2007]

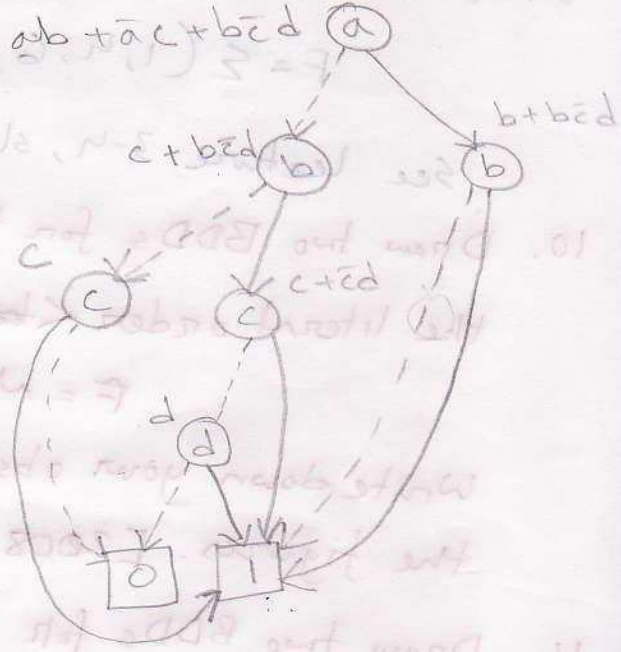
ii)  $F = ab + \bar{a}c + b\bar{c}d$  [2006]

iii)  $X = \bar{A}BC + A\bar{B}C + \bar{B}\bar{C}D$  [In-course]

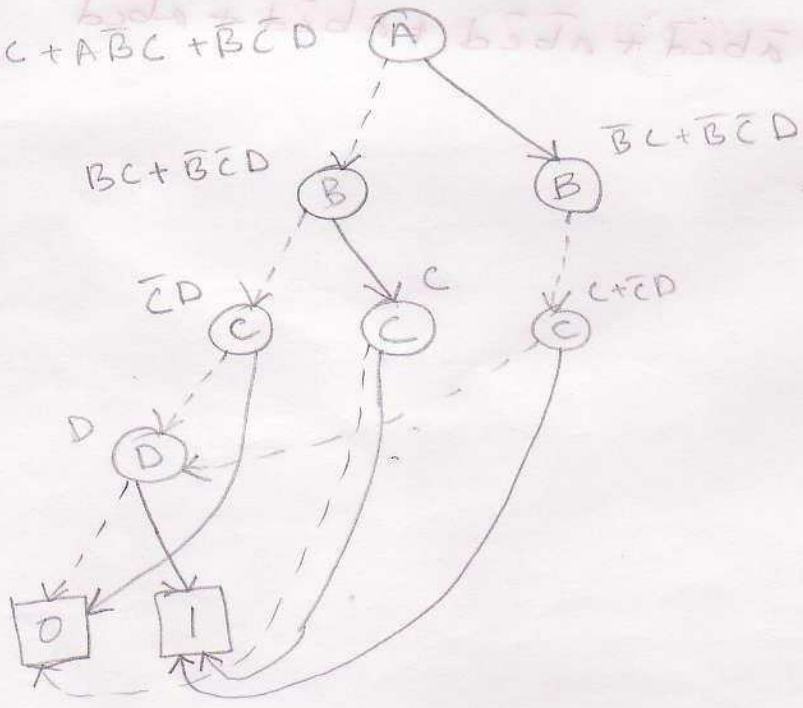
(i)  $AB + \bar{A}C + \bar{A}BD$



(ii)  $ab + \bar{a}c + b\bar{c}d$



(iii)  $\bar{A}BC + A\bar{B}C + \bar{B}\bar{C}D$



8. Using QM algorithm, minimize the following function:

$$F = \Sigma(0, 1, 2, 8, 10, 11, 14, 15) \quad [2007. Marks: 5]$$

See lecture 3-4, slide No. 11.

9. Calculate the prime implicant for the following function:

$$F = \Sigma(1, 4, 6, 7, 8, 9, 10, 11, 15) \quad [2006. Marks: 2/3]$$

See lecture 3-4, slide no. 16.

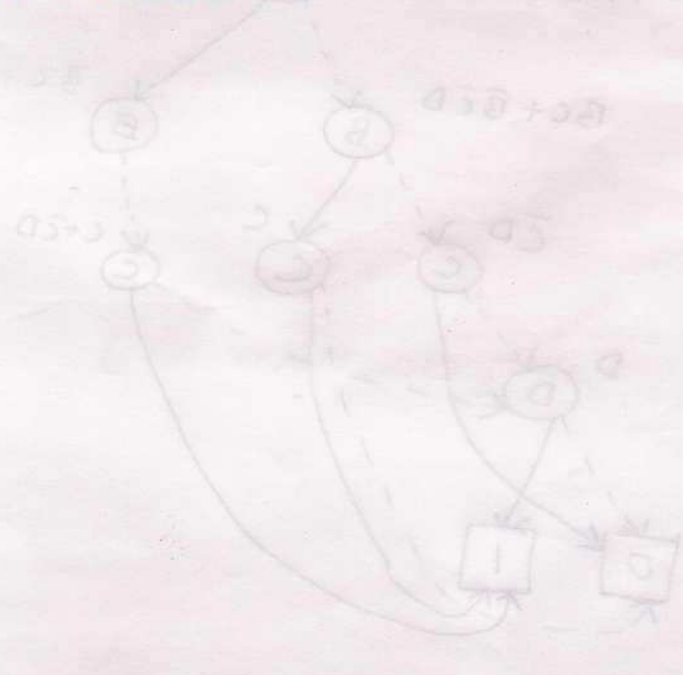
10. Draw two BDDs for the following function by considering the literal order  $\langle \text{bceda} \rangle$  and  $\langle \text{acbd} \rangle$

$$F = abc + \bar{a}c + b\bar{c}d$$

Write down your observation about the literal order from the figures. [2008. Marks: 4]

11. Draw two BDDs for the following expression for literal sequence  $\langle a, b, d, c \rangle$  and  $\langle b, d, c, a \rangle$ . [in-course 08-09. Marks: 4]

$$f_x = \bar{a}bcd + \bar{a}\bar{b}cd + ab\bar{c}d + abcd$$



## Lecture 5-6

### REVERSIBLE LOGIC SYNTHESIS

1. What is reversible logic (RL) and reversible gate/circuit?

~~An RL~~

A logic expression is "reversible" if <sup>each value in the</sup> ~~the ref~~ result of

the expression has a unique input value combination

A logic gate/circuit is ~~is~~ reversible if,

for any output  $y$ , there is a unique input  $x$  such that applying  $L(x) = y$ .

2. What is a garbage in reversible logic gate? [In-course 08-09. Marks: 0.5]

Every gate output that is not used as input to

another gate or as a primary output, is called garbage.

In other words, the unutilized outputs from a gate

are called garbage.

3. What are the advantages of reversible logic? [2008/2006. Marks: 0.5]

Reversible logic is a potential way to improve the energy efficiency of a circuit, as no input information is

lost and consequently no power is lost. <sup>(minimization)</sup> A bid logic ~~is~~

4. Write down the limitations of reversible logic. [In-course.]

1. Garbage is the most significant limitation of RL.
2. Feedback loop is strictly restricted in RL.

5. Prove that at least two garbage output will be generated to realize a reversible full-adder circuit. [2008, Marks: 2]

From the following truth table of a full-adder circuit, we can find that observe that <sup>for</sup> the 2nd, 3rd and 5th or the 4th, 6th and 7th output combinations, ~~cannot~~ <sup>have</sup> be the no unique input combinations can be dete found.

| Input |   |          | Output                               |  |
|-------|---|----------|--------------------------------------|--|
| A     | B | $C_{in}$ | $S_{out} = A \oplus B \oplus C_{in}$ | $C_{out} = AB \oplus BC_{in} \oplus C_{in}A$ |
| 0     | 0 | 0        | 0                                    | 0  |
| 0     | 0 | 1        | 1                                    | 0  |
| 0     | 1 | 0        | 1                                    | 0  |
| 0     | 1 | 1        | 0                                    | 1  |
| 1     | 0 | 0        | 1                                    | 0  |
| 1     | 0 | 1        | 0                                    | 1  |
| 1     | 1 | 0        | 0                                    | 1  |
| 1     | 1 | 1        | 1                                    | 0  |

Let's consider the case of 2nd, 3rd and 5th rows.

To make the output combinations unique, let's consider the first input bit A (arbitrarily) and take it as a garbage output. Then the input-output combination will look as follows!



| Input |   |          | Output |           |               |
|-------|---|----------|--------|-----------|---------------|
| A     | B | $C_{in}$ | S      | $C_{out}$ | $C_{out} = A$ |
| 0     | 0 | 1        | 1      | 0         | 0             |
| 0     | 1 | 0        | 1      | 0         | 0             |
| 1     | 0 | 0        | 1      | 0         | 1             |

Still, the 1st and 2nd output combinations are the same. So, we take another input bit B as a second garbage:

| Input |   |          | Output |           |               |               |
|-------|---|----------|--------|-----------|---------------|---------------|
| A     | B | $C_{in}$ | S      | $C_{out}$ | $C_{out} = A$ | $C_{out} = B$ |
| 0     | 0 | 1        | 1      | 0         | 0             | 0             |
| 0     | 1 | 0        | 1      | 0         | 0             | 1             |
| 1     | 0 | 0        | 1      | 0         | 1             | 0             |

Now, the output combinations are unique and the unique combination for each output combination can be found. Similarly, the 4th, 6th and 7th output combinations of the aforementioned full-adder circuit can be made unique by taking these two garbages.

Thus, it can be said that to realize a reversible full-adder det, a minimum of two garbage output will be generated.

6. Realize the following expressions with using Toffoli and NOT gate only:

NOT gate only:

i)  $X = \overline{ab+bc} \oplus \overline{cd+e}$  [2008]

i)  $X = (A+B) \oplus (CD+EF)$  [In-course]

ii)  $X = \overline{ab+bc} \oplus (cd+e)$  [2006]

[For Toffoli gate,  $I_v = (A, B, C)$

$O_v = (P, Q, R)$

where  $P = A$ ,

$Q = B$ ,

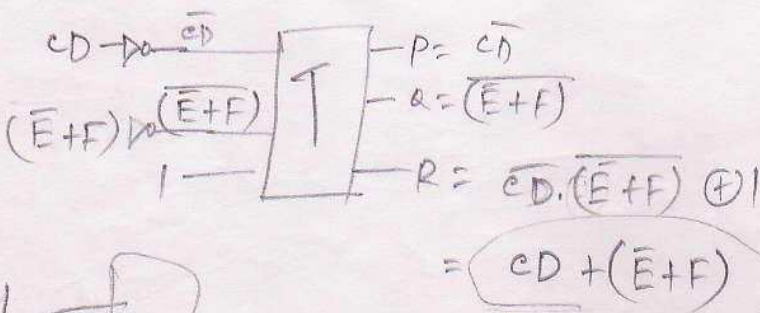
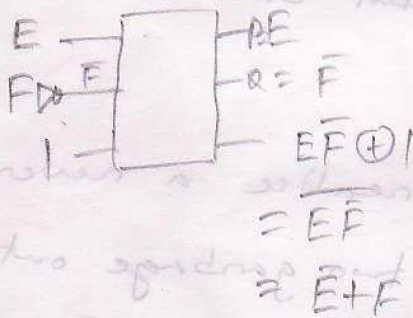
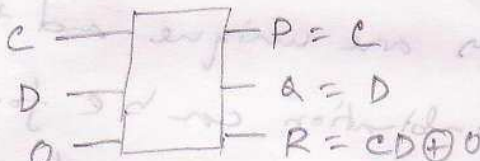
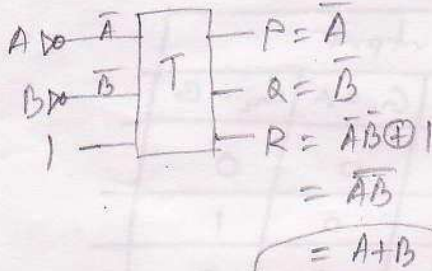
$R = AB \oplus C$

$A \rightarrow A$

$B \rightarrow B$

$C \rightarrow AB \oplus C$

i)



Note:  
 कागज सुखाना solve करके;  
 छात्र verify करे।

1+1

7. Realize the following expression with Peres and NOT gate only: [2007, Marks: 3]

$$X = \overline{abc} \oplus bc$$

[For Peres Gate,  $I_v = (A, B, C)$

$$O_v = \begin{cases} P = A, \\ Q = A \oplus B, \\ R = AB \oplus C \end{cases}$$

$$\begin{matrix} A & \text{---} & A \\ B & \text{---} & A \oplus B \\ C & \text{---} & AB \oplus C \end{matrix}$$

8. Draw the reversible ckt for the following expression using Fredkin Gates and Not gates only. [In-course 08-09, Marks: 4]

$$F = \overline{A \overline{B} \oplus \overline{C} D} + BCD + \overline{C} D \oplus EF$$

[For Fredkin Gate,  $I_v = (A, B, C)$

$$O_v = \begin{cases} P = A, \\ Q = \overline{A} B \oplus AC, \\ R = \overline{A} C \oplus AB \end{cases}$$

8. What are the challenges of Reversible Logic Design? [In-course 08-09, Marks: 0.5]

Examples of AOI:  
 AND-OR-Invert (AOI) gates are two level combinational logic functions constructed from the combination of one or more AND gates followed by a NOR gate.



# Lecture - 7

## SIMULATION & COMBINATIONAL NETWORK DELAY

1. What are the combinational network delays? How can we remove them? [2007 Marks: 2]

The combinational network delays consist of

### 1. Gate delay:

Transistors that are too small to drive the gate's load, particularly if the gate fans out to a number of other gates, may cause one gate to run much more slowly than all other gates in the system.

### 2. Path delay:

If some paths are significantly longer than the others, the long paths will determine maximum clock rate.

## How to eliminate delays:

### 1. Removing Gate delay:

1. The transistors of the driving gate can be enlarged.
2. The logic can be redesigned to reduce the gate's fanout.

### 2. Removing Path delay:

1. Speed up a delay gate on the critical path (the path which creates the longest delay).

2. If there is more than one critical path, speed up all of them.

3. Speed up cutset through critical path.

2. How can we measure the delay of a gate? [In-course. Marks: 2]

Delay of a gate  $T_{gate} = T_{intrinsic} + C_{load} * T_{load}$

where,  $T_{gate} = T_{intrinsic} + C_{load} * T_{load}$

$T_{intrinsic}$  = Intrinsic gate delay (caused by parasitics)

$C_{load}$  = The actual load in some units, e.g. pF

$T_{load}$  = The delays per load in some units, e.g. ns/pF.

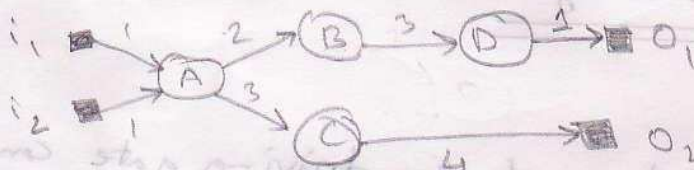
3. Discuss critical path and false path with examples.

[2008, 2007, 2006. Marks: 2]

Critical path:

The longest delay path in a ckt is known as the critical path, since that path limits system performance

For example, in the following delay graph, the critical paths are  $i_1 \rightarrow A \rightarrow C \rightarrow O_2$  and  $i_2 \rightarrow A \rightarrow C \rightarrow O_2$



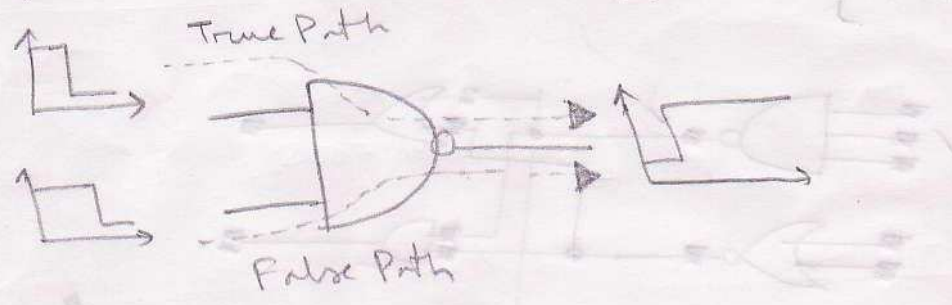
False Path:

A false path is a path which cannot be exercised due to Boolean gate conditions.

For example, in the following figure, the upper input goes low followed by the lower input. As either input going low causes the NAND's output to go high, the high-to-low transition of the latter input doesn't affect the gate's output

and is called a false path.

False paths cause pessimistic delay estimates.



4. Define Simulation. Differentiate between switch level simulation and circuit simulation. [2008, Marks: 2]

Simulation:

Simulation is a design validation tool for both checking a circuit's function and other parameters such as performance.

Diff. between switch level & ckt simulation:

| Switch level simulation  | Ckt. Simulation   |
|--|---|
| 1. Used for function verification of transistors in a ckt.                           | 1. Used to verify the entire CMOS ckt. and to detect errors in the ckt. |
| 2. Can accurately simulate a ckt. consisting of hundreds / thousands of transistors. | 2. Can operate accurately only for small ckt.                           |



## Lecture 7 (2<sup>nd</sup> Part)

How to deal with fan-out problem? [2008, Marks: 2]

OR, Discuss about the ways to drive large fan-out in a circuit. [In-course 08-09, Marks: 2]

1. Increase sizes of driver transistors.
2. Redesign the logic to reduce the gate's fan-out by adding intermediate buffers.

Why and how do we reduce critical path length?

We reduce critical path length to improve system performance.

Critical path length can be reduced by:

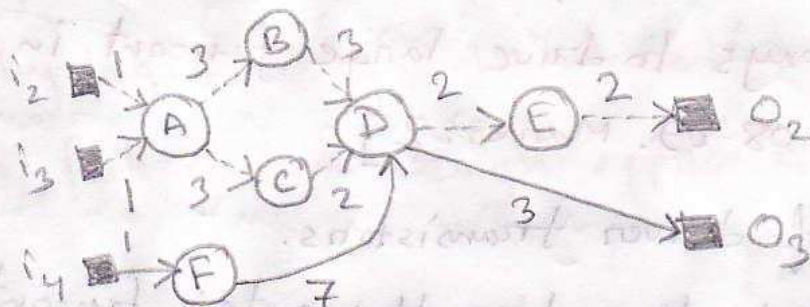
1. Speed up

1. Speeding up gates on the critical path by increasing transistor sizes or reducing wiring capacitance.
2. Redesigning the logic along the critical path to use a faster gate configuration by rewriting the function to reduce the number of logic levels.

[See lecture 7 slides #108]



9. What is critical path delay? Calculate the critical path delay for the following circuit: [In-course 05-06. Marks: 2]



The delay along the critical path is called the critical path delay.

The critical path in the given circuit is  $i_4 \rightarrow F \rightarrow D \rightarrow E \rightarrow O_2$  and the critical path delay is  $(1+7+2+2) = 12$ .

10. What are the advantages and disadvantages of the following simulators?

1. Circuit Simulator
2. Switch Level Simulator
3. Timing Simulator
4. Logic/Gate Level Simulator
5. Mixed Mode Simulator

[see lecture 7 slides 4 to 8.]

# Lecture 8

## STATIC COMPLEMENTARY GATE STRUCTURE

1. What is combinational logic?

Combinational logic is a type of digital logic which is implemented by boolean circuits, where the output is a pure function of the present input only.

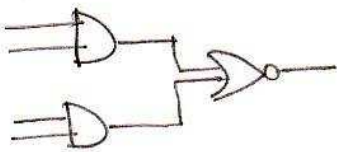
2. What is sequential logic?

Sequential logic is a type of logic ckt whose output depends on not only the present input but also on the history of the input.

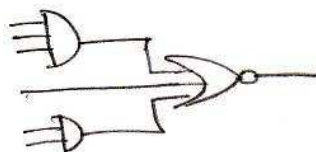
3. What is AOI? Give example. [In-course, Marks: 2]

AOI (AND-OR-Invert) logic and AOI gates are two-level compound (or complex) logic functions constructed from the combination of one or more AND gates followed by a NOR gate.

Examples of AOI:



2-2 AOI



3-1-2 AOI

4. Construct the pull-up and pull-down of the following expressions!

[marks: 1.5/2 each]

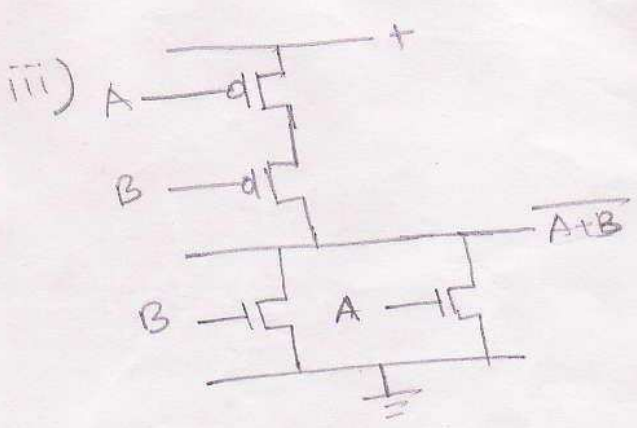
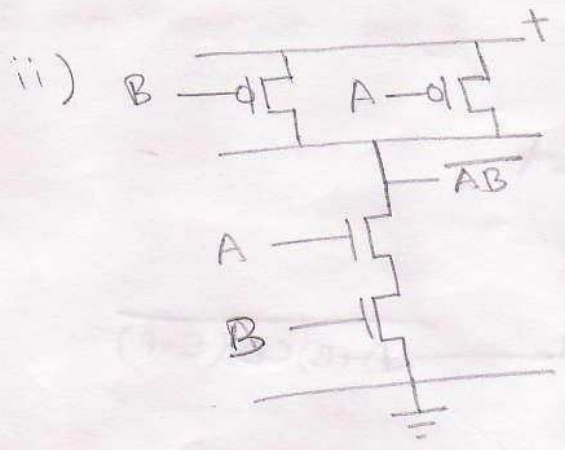
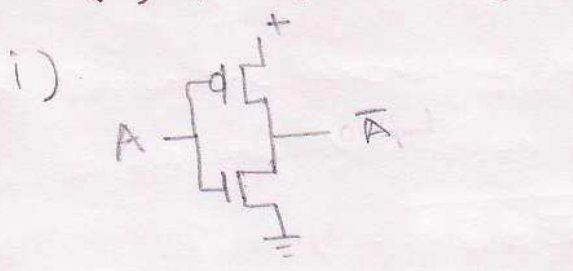
- i)  $X = \bar{A}$  (Not Gate/Inverter)
- ii)  $X = \overline{AB}$  (NAND Gate)
- iii)  $X = \overline{A+B}$  (NOR Gate)
- iv)  $X = \overline{AB+BC+DEF}$

Note!

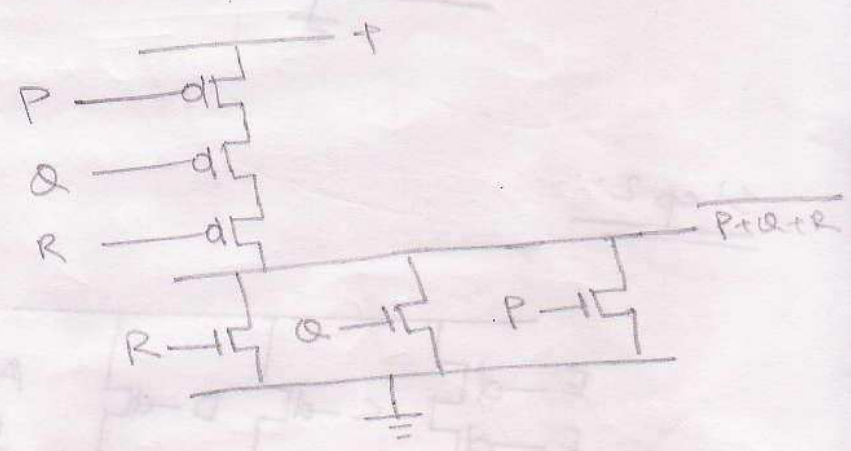
- 1. +V<sub>cc</sub> & Ground
- 2. Pull-up -> pmos -> bubble
- 3. Series connection -> OR input
- parallel -> OR output

v)  $X = \overline{(A+B)CD(E+F)}$  [2008], 2007

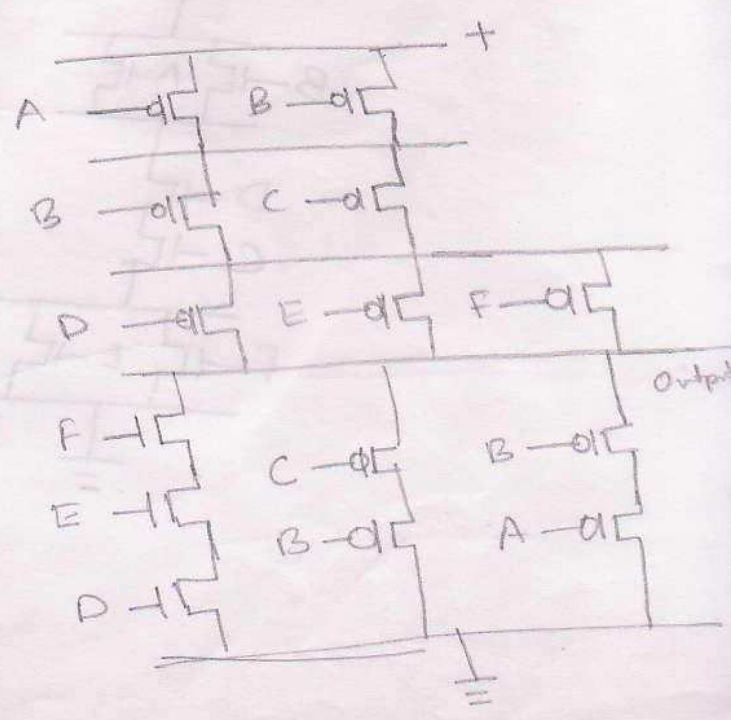
vi)  $X = \overline{abc+def}$  [2006] (vii)  $F = \overline{(A+B+C)(B+D)(A+D)}$  [In-course 08-09]



iv)  
Step 1: Let,  $X = \overline{P+Q+R}$



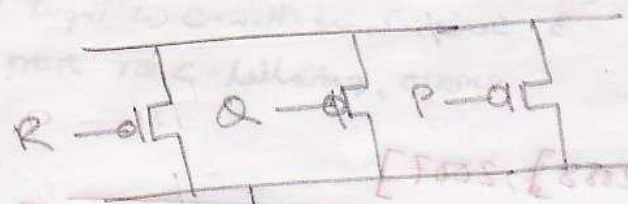
Step 2:



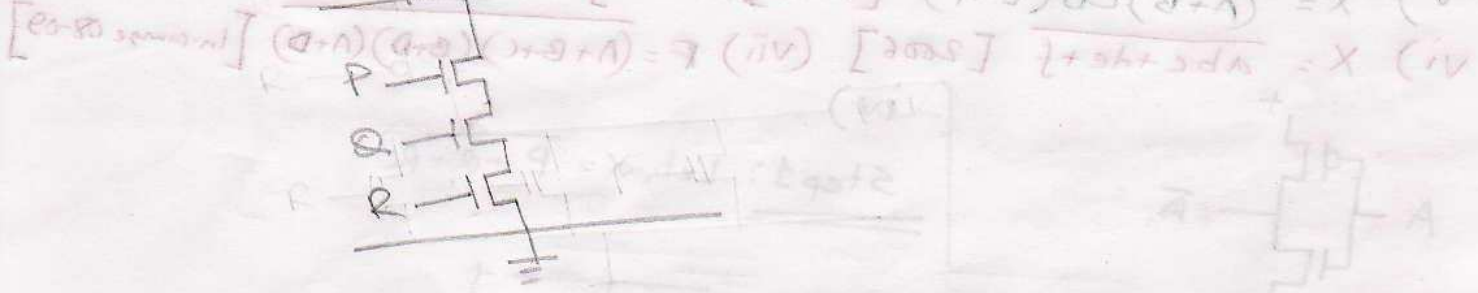
Example: Simplify the following circuit by using the first two laws of Boolean algebra

(v)  $X = (A+B)CD(E+F)$

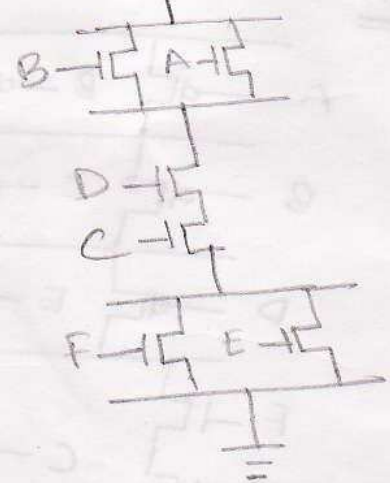
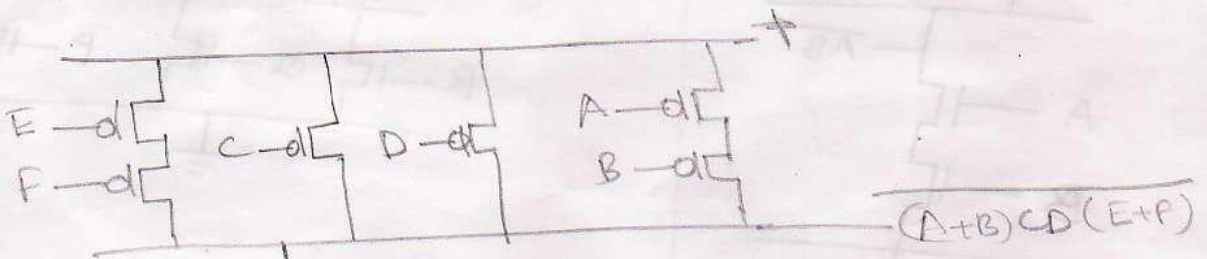
Step 1: Let,  $X = PQR$



- (i)  $\bar{A} = X$  (NOT gate)
- (ii)  $\overline{AB} = X$  (NAND gate)
- (iii)  $\overline{A+B} = X$  (NOR gate)
- (iv)  $X = AB+BC+CA$
- (v)  $X = (A+B)CD(E+F)$
- (vi)  $X = ABC+ACB+BCA$



Step 2:



## Lecture 8 (2<sup>nd</sup> Part)

Why designing gates for logic function is non-trivial?

Because,

1. Logic gates may not be <sup>available</sup> in the library for all logic expressions.
2. A logic expression may map into gates that consume a lot of area, delay or power.

What do you understand by completeness of functions?

~~A function~~ A set of functions  $f_1, f_2, \dots$  is complete if and only if every Boolean function can be generated by a combination of the functions.

For example, NAND and NOR are complete sets, whereas  $\{\text{AND, OR}\}$  is not complete.

## Lecture 9

### MOS

1. Write down the properties of enhancement mode of N-MOS transistor. [2006. Marks: 3]

1.  $V_{\text{threshold}} = 1V$
2. The semiconductor surface between the source and drain is doped with p-type impurity.
3. The n-MOS device is OFF when  $V_{gs} = 0V$ .

2. Write down the properties of <sup>depletion</sup> enhancement mode of pMOS transistor. [In-course: Marks: 2]

1.  $V_{\text{threshold}} = -4V$
2. The semiconductor surface between the source and drain is doped with n-type impurity.
3. The PMOS device is turned ON when  $V_{gs} = 0V$ .

3. Clearly describe the basic operations of nMOS enhancement mode. [2006. Marks: 2]

OR, Discuss about different types of status of nMOS enhancement mode with appropriate diagrams.

Three basic operations:

1. Cut-off / subthreshold / weak-inversion mode
2. Non-saturated / triode / linear region / ohmic mode
3. Saturated / active mode.

1. Cut-off:  $V_{gs} > V_t$  and  $V_{ds} = 0$  |  $V_t \neq 0$

Since  $V_{ds} = 0$ , no current will flow through the channel.

2. Non-saturated:  $V_{gs} > V_t$  and  $V_{ds} < V_{gs} - V_t$  |  $V_{ds} \neq 0$

Channel exists as well as electricity is flowing, but not in the maximum level. So, voltage should be increased. The current flow will be continued until

$$V_{ds} > V_{gs} - V_t$$

3. Saturated:  $V_{gs} > V_t$  and  $V_{ds} \geq V_{gs} - V_t$

This state will be continued until  $V_{ds} < V_{gs} - V_t$ .

4. What is threshold voltage? [In course 08-09. Marks: 1]

Threshold voltage is the voltage at which a MOS device begins to conduct (Turn ON).

The input potential is called threshold voltage,  $V_t$ .

5. What is transit time? Establish the relationship between  $V_{ds}$  and  $t_{tr}$ . [2008, 2006. Marks: 2]

Transit time:

It is the time which the electron takes to flow from drain to source through the channel of a MOS transistor. This time increases when the voltage between the drain and source decreases.

## Relationship among $V_{ds}$ , $E_{ds}$ , $I_{ds}$ !

We know, transit time  $\tau = L/v$  [where  $L$  = length of the channel  
 $\mu$  = Electron or hole mobility]

$$= L/(\mu E_{ds})$$

$$= L^2/(\mu V_{ds})$$

$$\therefore \frac{L}{\mu E_{ds}} = \frac{L^2}{\mu V_{ds}}$$

$$\Rightarrow V_{ds} = LE_{ds}$$

Again - Charge induced into channel ( $Q_c$ )

$$I_{ds} = \frac{\text{Charge induced into channel } (Q_c)}{\text{Transit time } (\tau)}$$

$$\Rightarrow \tau = \frac{Q_c}{I_{ds}}$$

$$\Rightarrow \frac{L^2}{\mu V_{ds}} = \frac{Q_c}{I_{ds}}$$

$$\Rightarrow I_{ds} = \frac{Q_c \mu V_{ds}}{L^2}$$

$$\Rightarrow I_{ds} = \left( \frac{Q_c \mu}{L} \right) E_{ds}$$



6. What are the differences between BJT and MOS? [2006, Marks: 2]

| BJT   | MOS   |
|---|---|
| 1. High Static power dissipation.                           | 1. Low Static power dissipation.                        |
| 2. Low packing density.                                     | 2. High packing density.                                |
| 3. Complex structure.                                       | 3. Simpler structure.                                   |
| 4. Implementation of dynamic logic is not permitted.        | 4. Implementation of dynamic logic is permitted.        |
| 5. Faster   | 5. Slower.  |
| 6. Requires large area.                                     | 6. Requires small area.                                 |
| 7. According to power-speed product, BJT is not preferable. | 7. According to power-speed product, MOS is preferable. |

7. Show the supremacy of MOS over BJT with an appropriate example. [2008, 2007, Marks: 2]  
 OR, with appropriate example, prove the supremacy of MOS over BJT.

Though the speed of BJT is as better than the MOS, MOS has some other primitives that lead to prefer MOS over BJT.

MOS consumes less power than BJT and requires less area. Its structure is simpler than BJT. Speed-power factor is the most important point to select MOS instead of BJT.